ADHESIVE, ADHESIVE SHEET, AND PROCESS FOR PRODUCING OF ELECTRONIC COMPONENTS

ABSTRACT

In a conventional adhesive sheet laminated with a die attachment film, the die attachment film sometimes drops off from the die chip at the time of pick-up after die chip formation by dicing a wafer. The present invention provides an adhesive including a (meth)acrylate ester polymer, a urethane acrylate oligomer having 4 or more vinyl groups, and silicone microparticles. Another aspect of the invention provides a process for producing electronic components, the process including: a wafer-pasting step of pasting a wafer on a surface of a die attachment film of an adhesive sheet; a dicing step of dicing the wafer into die chips; and a pick-up step of peeling the die attachment film from the adhesive layer after the dicing step, and picking up the die chip together with the die attachment film.

[Fig. 1]